

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A substrate-based assembly for carrying optical and/or electrical components, the substrate-based assembly comprising a packaging layer, wherein the packaging layer comprises a glass material having both organic and inorganic components.
2. (Original) A substrate-based assembly according to Claim 1 wherein the glass material includes an organic component which polymerises by cross-linking.
3. (Previously Presented) A substrate-based assembly according to claim 1 wherein the glass material includes an organic component which polymerises under thermal or photo treatment.
4. (Previously Presented) A substrate-based assembly according to claim 1 wherein the glass material includes at least one of an epoxy component, aluminium oxide and silicon oxide.
5. (Previously Presented) A substrate-based assembly according to claim 1 wherein the glass material comprises an inorganic matrix provided at least in part by a metal alkoxide or salt, the metal alkoxide or salt each being hydrolysed in provision of the inorganic matrix.
6. (Original) A substrate-based assembly according to claim 5 wherein the metal alkoxide or salt is based on groups 3A, 3B, 4B and/or 5B of the Periodic Table.
7. (Previously Presented) A substrate-based assembly according to claim 1 wherein the glass material includes at least one hydrocarbon compound from the group comprising acrylates, epoxides, alkyls, alkenes, and aromatic groups.
8. (Previously Presented) A substrate-based assembly according to claim 1 wherein the coefficient of thermal expansion of the packaging layer approaches that of the substrate material.

9. (Previously Presented) A substrate-based assembly according to claim 1 which further comprises electrical interconnect material for providing electrical connection to at least one component packaged by the packaging layer.

10. (Original) A substrate-based assembly according to Claim 9 wherein the coefficient of thermal expansion of the packaging layer approaches that of the electrical interconnect material.

11. (Previously Presented) A substrate-based assembly according to Claim 8 wherein the coefficient of thermal expansion of the packaging layer differs from the coefficient of thermal expansion of the electrical interconnect material and/or the substrate material by not more than 15 parts per million.

12. (Previously Presented) A substrate-based assembly according to claim 9 which further comprises at least one contact pad for a wire bond to the at least one component, the electrical interconnect material being present in said contact pad or wire bond.

13. (Previously Presented) A substrate-based assembly according to claim 9 which further comprises at least one mounting pad for mounting the at least one component, the electrical interconnect material being present in said mounting pad.

14. (Previously Presented) A substrate-based assembly according to claim 1, comprising a bump bonded optical component.

15. (Previously Presented) A substrate-based assembly according to claim 1 wherein the material of the packaging layer is lithographically patterned.

16. (Original) A substrate-based assembly according to Claim 15 wherein the material of the packaging layer comprises at least one organic material which photopolymerizes, the at least one organic material being selected from the group comprising acrylates, epoxides, alkyls, alkenes, and aromatic groups.

17. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging material has a processing temperature of not more than 450°C.

18. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging material has a processing temperature of not more than 200°C.

19. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging material has a processing temperature of not more than 150°C.

20. (Previously Presented) A substrate-based assembly according to Claim 17 wherein the packaging material is fabricated from a material comprising a polymerisation initiator.

21. (Previously Presented) A substrate-based assembly according to claim 1 which comprises at least one optical component and at least one electronic device.

22. (Original) A substrate-based assembly according to Claim 21 wherein the at least one electronic device comprises an integrated circuit.

23. (Previously Presented) A substrate-based assembly according to claim 1 which comprises at least one active optical component and at least one passive optical component.

24. (Previously Presented) A substrate-based assembly according to claim 1 having a substrate comprising at least one material from the group comprising silicon, glass, composite materials, ceramics and printed circuit board.

25. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer is a passivation layer.

26. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer is a planarisation layer.

27. (Original) A substrate-based assembly according to Claim 26 wherein the planarisation layer provides an optical function in use of the assembly.

28. (Original) A substrate-based assembly according to Claim 27 wherein the optical function comprises waveguiding.

29. (Previously Presented) A substrate-based assembly according to Claim 25 wherein the planarisation layer is provided with at least one aperture to give access to an electrical interconnect structure.

30. (Previously Presented) A substrate-based assembly according to Claim 25 wherein one or more components or devices is mounted at least partially on the planarisation layer and the planarisation layer provides support to said one or more components or devices.

31. (Previously Presented) A substrate-based assembly according to claim 1 comprising at least two packaging layers, each of said at least two packaging layers comprising a glass material having both organic and inorganic components.

32. (Original) A substrate-based assembly according to Claim 31 wherein the refractive index of a first of the at least two packaging layers is different from the refractive index of a second of the at least two packaging layers.

33. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer, or at least one packaging layer, transmits optical radiation in use of the assembly.

34. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer, or at least one packaging layer, provides a waveguiding function in use of the assembly.

35. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer, or at least one packaging layer, provides an alignment feature for use in aligning an optical component in the assembly.

36. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer, or at least one packaging layer, provides refractive index matching in use of the assembly.

37. (Previously Presented) A substrate-based assembly according to claim 1 wherein the packaging layer, or at least one packaging layer, provides bonding between optical components in the assembly.

38. (Previously Presented) A substrate-based assembly according to claim 1 comprising at least one active optical component.

39. (Original) A substrate-based assembly according to Claim 38 wherein the active optical component comprises a laser or a tunable optical source.

40. (Previously Presented) A substrate-based assembly according to claim 38 wherein the at least one active optical component is bump-bonded in the assembly.

41. (Previously Presented) A substrate-based assembly according to claim 38 wherein the at least one active optical component is flip-chip mounted in the assembly.

42. (Original) A substrate-based assembly according to Claim 41, further comprising an optical modulator, external to the laser or tunable optical source.

43. (Previously Presented) A substrate-based assembly according to claim 1 wherein the substrate-based assembly comprises a thick substrate-based assembly.

44. (Previously Presented) A substrate-based assembly according to claim 1 wherein the substrate-based assembly has a thickness in the range from 1 micron to 1 millimetre.

45. (Previously Presented) Opto-electronic equipment comprising a substrate-based assembly according to claim 1.

46. (Currently Amended) A method of packaging making a substrate-based assembly as described in claim 1 by packaging a substrate-based assembly according to a method comprising, ~~which method comprises the step of~~ providing a packaging layer comprising a glass material having both organic and inorganic components.

47. (Currently Amended) ~~A~~ The method of packaging a substrate-based assembly according to Claim 46, wherein the method further comprises the step of lithographic processing of the packaging layer.

48. (Currently Amended) A method of fabricating a substrate-based assembly as described in claim 1, the assembly comprising at least one optical component mounted in relation to a substrate, the method comprising:

lithographic processing of each fabricated layer of the substrate-based assembly, at least one fabricated layer comprising a glass material having both organic and inorganic components.

49. (Currently Amended) A method of fabricating a substrate-based assembly, the assembly being according to Claim 1, using bump bonding material to bump bond at least one optical component to a mounting pad, wherein the method comprises ~~the steps of~~:

a) maintaining the temperature of the bump bonding material above a softening temperature for the material and micro-manipulating the component in relation to the mounting pad; and

b) lowering the temperature of the bump bonding material to below said softening temperature so as to achieve bump bonding.

50. (Currently Amended) A method of fabricating a substrate-based assembly as described in claim 1, the method comprising:

~~the step of~~ using gray scale lithography to fabricate a groove of tapered cross section in a packaging layer for mounting a fibre for optical coupling with an optical component, said packaging layer comprising a glass material having both organic and inorganic components.

51. (Currently Amended) A method of fabricating a substrate-based assembly according to Claim 1 which comprises ~~the step of~~ depth adjustment in a packaging layer.

52. (Currently Amended) A method of fabricating a substrate-based assembly according to Claim 51 wherein said ~~step of~~ depth adjustment comprises the use of a lithography mask having non-uniform optical density.

53. (Currently Amended) A method of fabricating a substrate-based assembly as described in claim 1, the method comprising:

~~the steps of~~ applying an electrical interconnect structure to a surface,
applying a ~~planarisation~~ planarization layer over the electrical interconnect structure; and
creating one or more apertures in the ~~planarisation~~ planarization layer to give access to the electrical interconnect structure,
said ~~planarisation~~ planarization layer comprising a glass material having both organic and inorganic components.